

bq25600, bq25600D PWR771 Evaluation Module

This user's guide provides detailed testing instructions for the bq25600 and bq25600D evaluation modules (EVM). Also included are descriptions of the necessary equipment, equipment setup, and procedures. The reference documentation contains the printed-circuit board layouts, schematics, and the bill of materials (BOM).

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1 Introduction

1.1 EVM Features

For detailed features and operation, see [Table 1](#) for a list of devices and their data sheets.

Table 1. Device Data Sheets

Device	Data Sheet	EVM Label	Variant
bq25600	SLUSCJ4	bq25600EVM-771	003
bq25600D	SLUSCJ4	bq25600DEVM-771	004

The bq25600(D) evaluation module (EVM) is a complete charger module for evaluating an I²C-controlled single NVDC-1 charge using the bq25600(D) device.

This EVM does not include the USB-to-GPIO or EV2300/EV2400 interface board. To evaluate the EVM, a USB-to-GPIO interface board must be ordered separately.

1.2 I/O Descriptions

[Table 2](#) lists the jumper connections available on this EVM.

Table 2. PWR771 EVM Connections

Jack	Description
J1-VAC	Input: positive terminal
J1-GND	Input: negative terminal (ground terminal)
J2-PMID	PMID pin connection, power bank output
J2-GND	Ground and power bank output negative terminal
J3	Output mini-USB port
J4-SYS	Connected to system
J4-GND	Ground
J5-BAT	Connected to battery pack
J5-BATSNS	Connected to battery pack for voltage sensing
J5-GND	Ground
J6	I ² C 4-pin connector
J7	USB-TO-GPIO connector

Table 3 lists the EVM jumper connections.

Table 3. EVM Jumper Connections and Shunt Installation

Jack	Description	bq25600 Setting	bq25600D Setting
JP1	D+ and PSEL pin selection	Short PSEL to low	Not installed
JP2	CE pin setting: pull low to enable the charge	Installed	Installed
JP3	SCL and OTG pin setting	Not installed	Not installed
JP4	STAT, PG, CE, INT, OTG pins internal pullup source (VSYS or BAT)	Short to VSYS	Short to VSYS
JP5	TS pin to GND	Not installed	Not installed
JP6	TS resistor divider pullup source (REGN) connection	Installed	Installed
JP7	Internal 10 k to GND to TS pin	Installed	Installed
JP8	BATSNS selection	Short to BAT	Short to BAT
JP9	QON and VSET pin setting	Not installed	Not installed
JP10	STAT pin setting	Installed	Installed
JP12	SDA and PG pin setting	Installed	Not installed
JP13	D+ and PSEL to J3	Not installed	Installed
JP14	D- and PG to J3	Not installed	Installed
JP15	D- and PG pin setting	Installed	Not installed
JP100	Add 1- μ F (C100) VBUS capacitor	Not installed	Not installed
JP101	Add 10- μ F (C101) PMID capacitor	Not installed	Not installed
JP103	Add 10- μ F (C103) SYS capacitor	Not installed	Not installed
JP104	Add 4.7- μ F (C104) BAT capacitor	Not installed	Not installed
S1	QON control	Default off	Default off
S2	Switch to short indicator LEDs	Default off	Default off

Table 4 lists the recommended operating conditions for this EVM.

Table 4. Recommended Operating Conditions

Symbol	Description	MIN	TYP	MAX	UNIT
Supply voltage, V_{VBUS}	Input voltage from AC adapter	3.9	5	14	V
Battery voltage, V_{BAT}	Voltage applied at V_{BAT} terminal	0	4.208	4.624	V
I_{BAT}	Fast charging current	0		2.5	A
I_{BATOP}	Discharging current through internal MOSFET	0		6	A
Supply current, I_{IN}	Maximum input current from AC adapter input	0		3.25	A

2 Test Summary

2.1 Equipment

This section includes a list of supplies required for testing this EVM.

- Power supply: Power supply #1 (PS#1): A power supply capable of supplying 5 V at 1 A is required. While this part can handle larger voltage and current, it is not necessary for this procedure.
- Load #1:
 - 4-quadrant supply, constant voltage < 4.5 V, A 0 – 20 V, 0 – 5 A, > 30-W system, DC electronic load and setting as constant voltage load mode
 - or
 - Kepco load: BOP 20 – 5M, DC 0 to ± 20 V, 0 to ± 5 A (or higher).
- Load #2: Use with Boost Mode, PMID to GND load, 10 Ω , 5 W or greater.
- Meters:
 - Six Fluke 75 multimeters, (equivalent or better)
 - or
 - Four equivalent voltage meters and two equivalent current meters. The current meters must be capable of measuring 5-A current.
- Computer: A computer with at least one USB port and a USB cable. The bq25600DEVM evaluation software must be properly installed.
- USB-to-GPIO Communication Kit: EV2300/EV2400 USB-based PC interface board.
- Software: Download [bqStudio](http://www.ti.com) from www.ti.com.
 1. Double click the *Battery Management Studio-1.3.20_Build2-Setup* installation file, follow the installation steps. The software supports the Microsoft® Windows® XP and Windows 7 operating systems.
 2. Copy the bq25600 bqz file to C:\ti\BatteryManagementStudio\config

2.2 Equipment Setup

Use the following instructions to set up the equipment:

1. Set PS#1 for 5-V DC, 1-A current limit and then turn off the supply.
2. Connect the output of PS#1 in series with a current meter (multimeter) to J1 (VBUS and GND).
3. Connect a voltage meter across TP1 (VBUS) and TP18 (GND).
4. Turn on the load, set it to constant voltage mode and set the output to 2.5 V.
5. Turn off (disable) the load.
6. Connect the load to J5 (BAT and GND), as shown in [Figure 2](#).
7. Connect one voltage meter across TP9 (BAT) and TP20 (GND) to measure the battery voltage and another voltage meter across TP28 and TP29 to measure the battery current sensing resistor voltage. The sensing resistor is 10 m Ω . It is also OK to use the optional current meter in series to measure the battery current.
8. Connect the EV2300/2400 USB interface board to the computer with a USB cable and from the I2C port to J8 with the 4-pin cable. The connections are shown in [Figure 1](#).

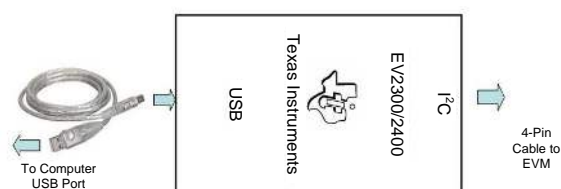
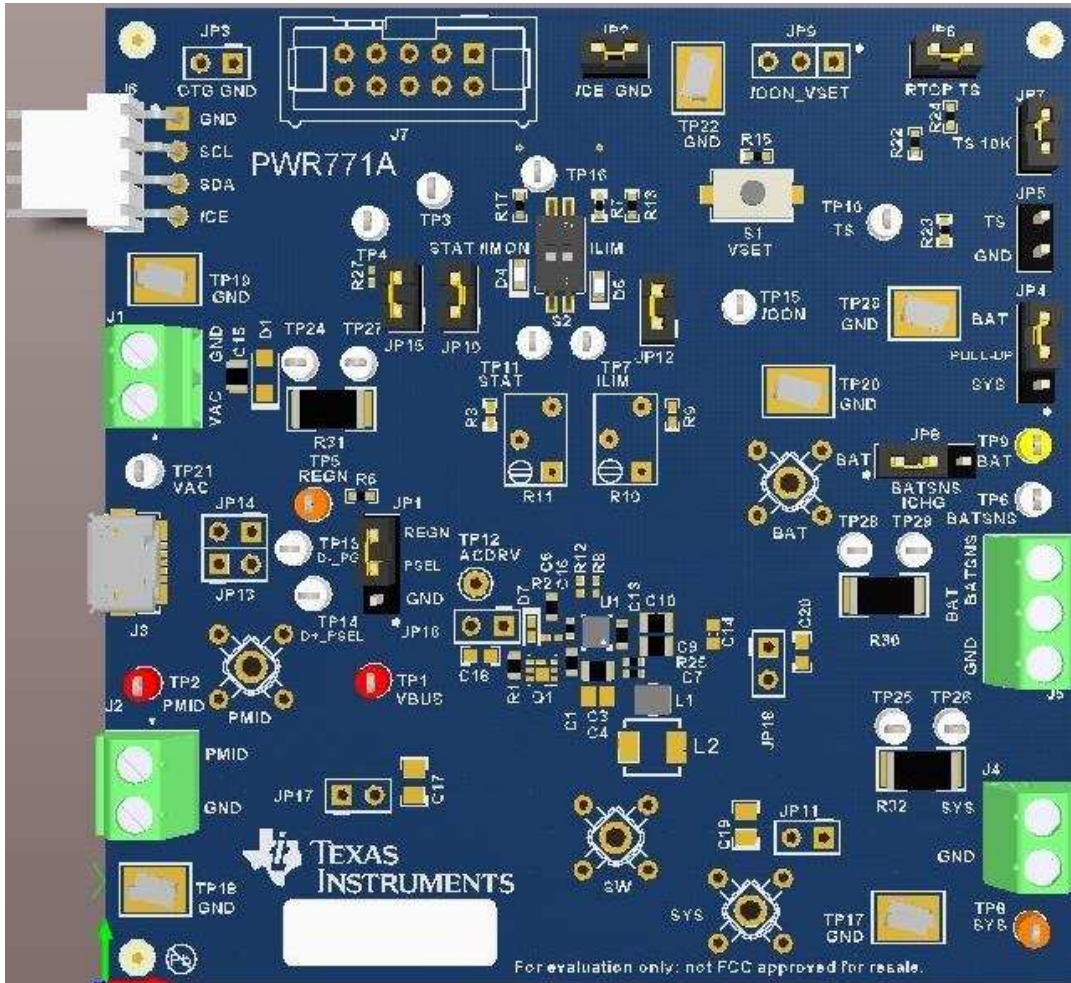


Figure 1. Connections of the EV2300/2400 Kit

- Install shunts as shown in [Table 3](#), or as shown in [Figure 2](#).



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Figure 2. Original Test Setup for bq25600xEVM

- Turn on the computer and launch the Battery Management Studio (bqStudio).
- Select *Charger* and bq25600 (or bq25600D, accordingly) evaluation software. [Figure 3](#) shows the main window of the software.

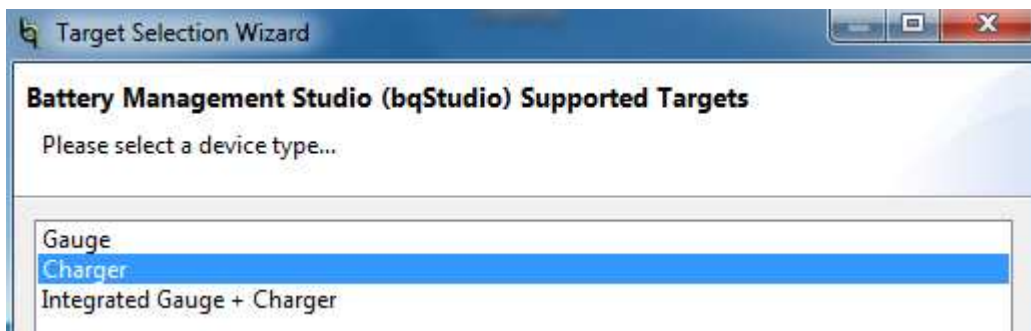


Figure 3. Selection Window of bqStudio Evaluation Software

2.3 Test Procedure

2.3.1 Current Settings

To turn on PS#1, measure $\rightarrow V_{\text{sys}}$ (TP8(SYS), TP17(GND)) = 3.65 (typical).

2.3.2 Charge Voltage and Current Regulation of VIN and Device ID Verification

Verify the outputs and IC for the EVM.

2.3.3 Charger Mode Verification

1. Enable Load #1 from [Section 2.2](#), Step 4 to 5.
2. Measure the voltage across J3 and J4 as follows:
 - Measure $\rightarrow V(\text{TP8}(\text{SYS}), \text{TP17}(\text{GND})) = 3.65 \text{ V}$ (typical)
 - Measure $\rightarrow V(\text{TP9}(\text{BAT}), \text{TP17}(\text{GND})) = 2.5 \text{ V}$ (typical)
 - Measure $\rightarrow \text{IBAT} = 75 \text{ mA}$ (typical) (= precharge current)
3. Change the load to 3.7 V:
 - Measure $\rightarrow V(\text{TP8}(\text{SYS}), \text{TP17}(\text{GND})) = 3.8 \text{ V}$ (typical)
 - Measure $\rightarrow V(\text{TP9}(\text{BAT}), \text{TP17}(\text{GND})) = 3.7 \text{ V}$ (typical)
 - Measure $\rightarrow \text{IBAT} = 1500 \text{ mA}$ (typical) (= fast charge current)
4. Adjust R10 to change the charging current.
5. Adjust R11 to change input current limit.
6. Turn off and disconnect Load #1.
7. Turn off and disconnect PS#1.

2.3.4 Boost Mode Verification

Follow these instructions for boost mode verification:

1. Do not install JP3.
2. If the constant voltage load connected from BAT+ to GND is not a 4-quadrant supply (sources current), remove the load and use the power source disconnected in step one, set to 3.7 V and 2-A current limit, and connect between BAT+ and GND.
3. Apply 10 Ω (5 W or greater) across J2 PMID(+) to GND(-).
4. Verify V_{PMID} to GND on J2.
Measure $\rightarrow V_{\text{PMID}} = 5.15 \text{ V}$ (typical).
5. Turn off and disconnect the power supply.
6. Remove the 10- Ω resistor at PMID.

2.3.5 Helpful Tips

- The leads and cables to the various power supplies, batteries and loads have resistance. The current meters also have series resistance. The charger dynamically reduces charge current depending on the voltage sensed at its VBUS pin (using the VINDPM feature), BAT pin (as part of normal termination), and TS pin (through its battery temperature monitoring feature via battery thermistor). Therefore, voltmeters must be used to measure the voltage as close to the IC pins as possible instead of relying on the digital readouts of the power supply. If a battery thermistor is not available, make sure shunts JP9 and JP10 are in place.
- When using a source meter that can source and sink current as your battery simulator, TI highly recommends adding a large (1000+ μF) capacitor at the EVM BAT and GND connectors in order to prevent oscillations at the BAT pin due to mismatched impedances of the charger output and source meter input within their respective regulation loop bandwidths. Configuring the source meter for 4-wire sensing eliminates the need for a separate voltmeter to measure the voltage at the BAT pin. When using 4-wire sensing, always ensure that the sensing leads are connected in order to prevent accidental overvoltage by the power leads.
- For precise measurements of charge current and battery regulation near termination, the current meter in series with the battery or battery simulator should not be set to auto-range and may need be removed entirely. An alternate method for measuring charge current is to either use an oscilloscope with hall effect current probe or place a 1% or better, thermally capable (for example, 0.010 Ω in 1210 or larger footprint) resistor in series between the BAT pin and battery and measure the voltage across that resistor.

3 PCB Layout Guideline

Minimize the switching node rise and fall times for minimum switching loss. Proper layout of the components minimizing high-frequency current path loop is important to prevent electrical and magnetic field radiation and high-frequency resonant problems. This PCB layout priority list must be followed in the order presented for proper layout:

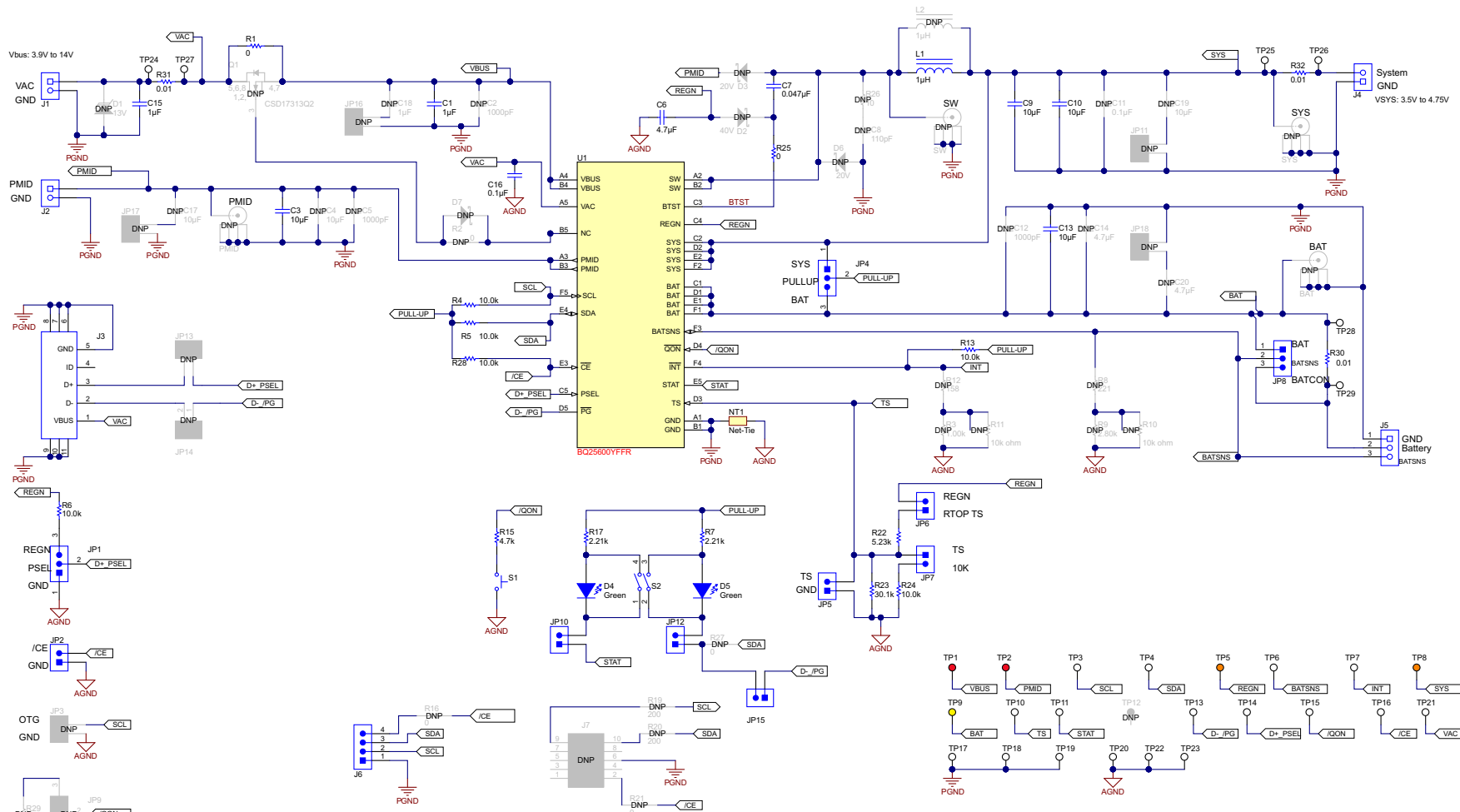
1. Place the input capacitor as close as possible to the PMID pin and GND pin connections and use the shortest copper trace connection or GND plane.
2. Put an output capacitor near to the inductor and the IC.
3. Decoupling capacitors should be placed next to the IC pins and make the trace connection as short as possible.
4. Place the inductor input terminal and SW pin as close as possible. Minimize the copper area of this trace to lower electrical and magnetic field radiation but make the trace is wide enough to carry the charging current. Do not use multiple layers in parallel for this connection. Minimize parasitic capacitance from this area to any other trace or plane.
5. It is OK to connect all grounds together to reduce PCB size and improve thermal dissipation.
6. Try to avoid ground planes in parallel with high frequency traces in other layers

See the EVM design for the recommended component placement with trace and via locations.

4 Board Layout, Schematic, and Bill of Materials

4.1 Schematic

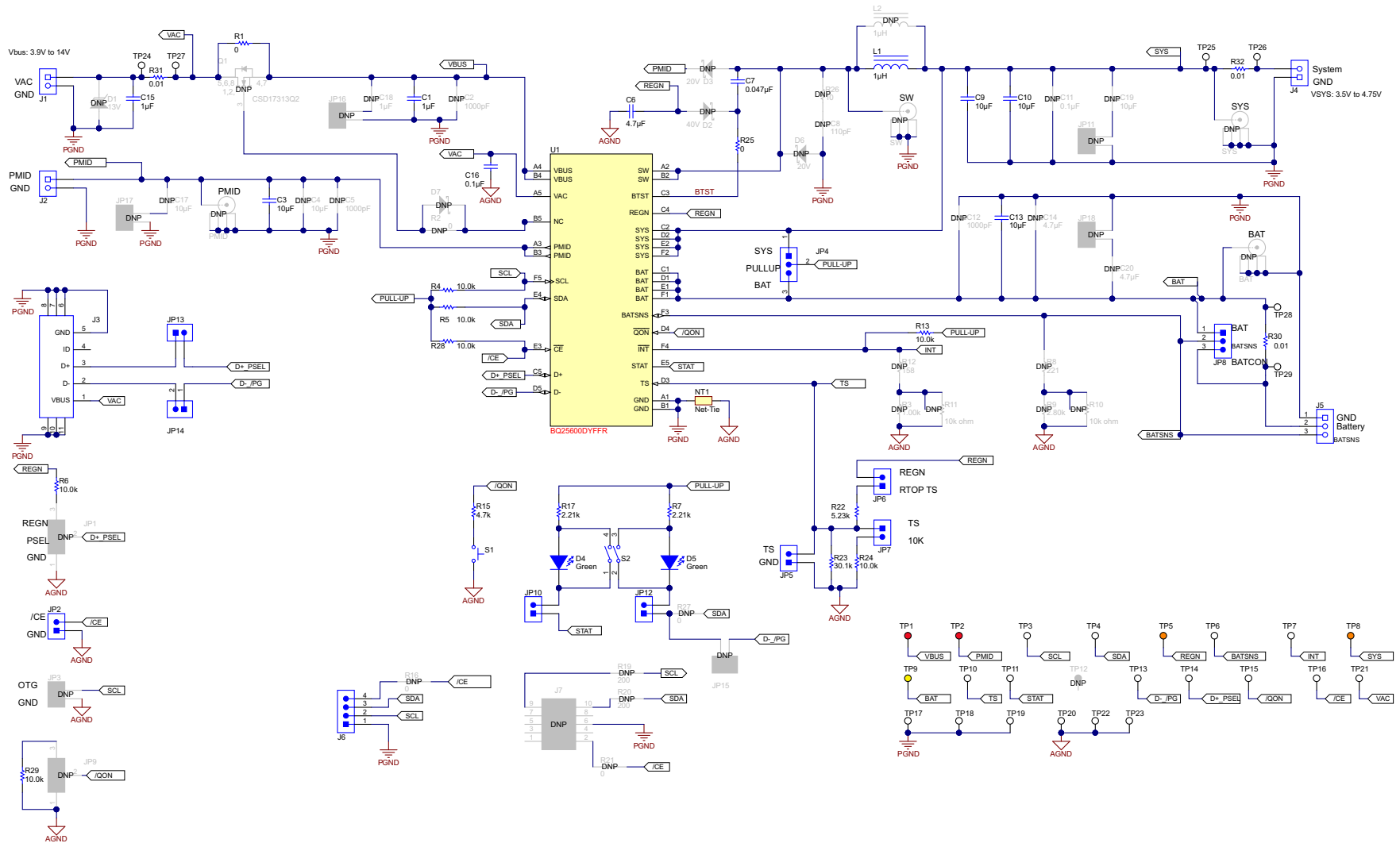
[Figure 4](#) shows the schematic for the bq25600 EVM.



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Figure 4. Schematic for bq25600 EVM

Figure 5 shows the schematic for the bq25600D EVM.



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Figure 5. Schematic for bq25600D EVM

4.2 Bill of Materials

Table 5 lists the bq25600EVM-771 BOM.

Table 5. bq25600EVM-771 Bill of Materials

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
!PCB	1		Printed Circuit Board		PWR771	Any		
C1	1	1 μ F	Capacitor, ceramic, 1 μ F, 35 V, \pm 10%, X5R, 0603	0603	GMK107BJ105KA-T	Taiyo Yuden		
C3	1	10 μ F	Capacitor, ceramic, 10 μ F, 25 V, \pm 10%, X5R, 0805	0805	GRM21BR61E106KA73L	Murata		
C6, C13	2	4.7 μ F	Capacitor, ceramic, 4.7 μ F, 16 V, \pm 10%, X5R, 0603	0603	GRM188R61C475KAAJ	Murata		
C7	1	0.047 μ F	Capacitor, ceramic, 0.047 μ F, 25 V, \pm 10%, X7R, 0402	0402	GRM155R71E473KA88D	Murata		
C9, C10	2	10 μ F	Capacitor, ceramic, 10 μ F, 10 V, \pm 10%, X7R, 0805	0805	GRM21BR71A106KE51L	Murata		
C15	1	1 μ F	Capacitor, ceramic, 1 μ F, 25 V, \pm 10%, X7R, 0805	0805	GRM219R71E105KA88D	Murata		
C16	1	0.1 μ F	Capacitor, ceramic, 0.1 μ F, 25 V, \pm 10%, X7R, 0402	0402	GRM155R71E104KE14D	Murata		
D4, D5	2	Green	LED, Green, SMD	1.6 \times 0.8 \times 0.8 mm	LTST-C190GKT	Lite-On		
H1, H2, H3, H4	4		Bumpon, Hemisphere, 0.44 \times 0.20, clear	Transparent Bumpon	SJ-5303 (CLEAR)	3M		
J1, J2, J4	3		Connector, terminal block, 2-POS, 3.81 mm, TH	Terminal block, 2 POS	1727010	Phoenix Contact		
J3	1		Connector, receptacle, Micro-USB Type B, R/A, bottom mount SMT	7.5 \times 2.45 \times 5 mm	0473460001	Molex		
J5	1		Terminal block receptacle, 3 \times 1, 3.81 mm, R/A, TH	Terminal block, 3 POS	1727023	Phoenix Contact		
J6	1		Header (friction lock), 100 mil, 4 \times 1, R/A, TH	4 \times 1 R/A header	22-05-3041	Molex		
JP1, JP4, JP8	3		Header, 100 mil, 3 \times 1, tin, TH	Header, 3-pin, 100 mil, tin	PEC03SAAN	Sullins Connector Solutions		
JP2, JP5, JP6, JP7, JP10, JP12, JP15	7		Header, 100 mil, 2 \times 1, tin, TH	Header, 2-pin, 100 mil, tin	PEC02SAAN	Sullins Connector Solutions		
L1	1	1 μ H	Inductor, 1 μ H, 3.2 A, 0.028 Ω , SMD	2.5 \times 2 mm	MPIM252010F1R0M-LF	Microgate		

Table 5. bq25600EVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
LBL1	1		Thermal transfer printable labels, 0.650" W x 0.200" H – 10,000 per roll	PCB label 0.650" H x 0.200" W	THT-14-423-10	Brady		
R1	1	0.005	Resistor, 0.005, 1%, 0.25 W, AEC-Q200 Grade 1, 0603	603	ERJ3LWFR005V	Panasonic		
R7, R17	2	2.21 k	Resistor, 2.21 k, 1%, 0.063 W, 0402	0402	CRCW04022K21FKED	Vishay-Dale		
R15	1	4.7 k	Resistor, 4.7 k, 5%, 0.063 W, 0402	0402	CRCW04024K70JNED	Vishay-Dale		
R22	1	5.23 k	Resistor, 5.23 k, 1%, 0.063 W, 0402	0402	CRCW04025K23FKED	Vishay-Dale		
R23	1	30.1 k	Resistor, 30.1 k, 1%, 0.063 W, 0402	0402	CRCW040230K1FKED	Vishay-Dale		
R25	1	0	Resistor, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
R30, R31, R32	3	0.01	Resistor, 0.01, 1%, 1 W, 2010	2010	WSL2010R0100FEA18	Vishay-Dale		
S1	1		Switch, normally open, 2.3-N force, 200-k operations, SMD	KSR	KSR221GLFS	C&K Components		
S2	1		Switch, SPST, 2 POS, 25 mA, 24 VDC, SMD	3.71 x 5.8 mm	218-2LPST	CTS Electrocomponents		
SH-JP1, SH-JP2, SH-JP4, SH-JP6, SH-JP7, SH-JP8, SH-JP10, SH-JP12, SH-JP15	9	1 x 2	Shunt, 100 mil, gold-plated, black	Shunt	SNT-100-BK-G	Samtec	969102-0000-DA	3M
TP1, TP2	2		Test point, miniature, red, TH	Red miniature test point	5000	Keystone		
TP3, TP4, TP6, TP7, TP10, TP11, TP13, TP14, TP15, TP16, TP21, TP24, TP25, TP26, TP27, TP28, TP29	17		Test point, miniature, white, TH	White miniature test point	5002	Keystone		
TP5, TP8	2		Test point, miniature, orange, TH	Orange miniature test point	5003	Keystone		
TP9	1		Test point, miniature, yellow, TH	Yellow miniature test point	5004	Keystone		

Table 5. bq25600EVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
TP17, TP18, TP19, TP20, TP22, TP23	6		Test point, compact, SMT	Testpoint_Keystone_Compact	5016	Keystone		
U1	1		BQ25600YFF, YFF0030ACAC (DSBGA-30)	YFF0030ACAC	BQ25600YFFR	Texas Instruments	BQ25600YFFT	Texas Instruments
C2, C5, C12	0	1000 μ F	Capacitor, ceramic, 1000 pF, 25 V, \pm 5%, C0G/NP0, 0402	0402	C1005C0G1E102J	TDK		
C4	0	10 μ F	Capacitor, ceramic, 10 μ F, 25 V, \pm 10%, X7S, 0805	0805	GRM21BC71E106KE11L	Murata		
C8	0	110 pF	Capacitor, ceramic, 110 pF, 25 V, \pm 5%, C0G/NP0, 0402	0402	GRM1555C1E111JA01D	Murata		
C11	0	0.1 μ F	Capacitor, ceramic, 0.1 μ F, 25 V, \pm 20%, X7R, 0402	0402	C1005X7R1E104M050BB	TDK		
C14, C20	0	4.7 μ F	Capacitor, ceramic, 4.7 μ F, 16 V, \pm 10%, X5R, 0603	0603	GRM188R61C475KAAJ	Murata		
C17	0	10 μ F	Capacitor, ceramic, 10 μ F, 25 V, \pm 10%, X5R, 0805	0805	GRM21BR61E106KA73L	Murata		
C18	0	1 μ F	Capacitor, ceramic, 1 μ F, 35 V, \pm 10%, X5R, 0603	0603	GMK107BJ105KA-T	Taiyo Yuden		
C19	0	10 μ F	Capacitor, ceramic, 10 μ F, 10 V, \pm 10%, X7R, 0805	0805	GRM21BR71A106KE51L	Murata		
D1	0	13 V	Diode, TVS, Uni, 13 V, W, SOD-123W	SOD-123W	PTVS13VS1UR,115	NXP Semiconductor		
D2	0	40 V	Diode, Schottky, 40 V, 0.38 A, SOD-523	SOD-523	ZLLS350TA	Diodes Inc.		
D3, D6	0	20 V	Diode, Schottky, 20 V, 1 A, 152AD	152AD	NSR10F20NXT5G	ON Semiconductor		
FID1, FID2, FID3, FID4, FID5, FID6	0		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	N/A		
J7	0		Header (shrouded), 100 mil, 5 \times 2, high-temperature, gold, TH	5 \times 2 shrouded header	N2510-6002-RB	3M		
JP3, JP11, JP13, JP14, JP16, JP17, JP18	0		Header, 100 mil, 2 \times 1, tin, TH	Header, 2-pin, 100 mil, tin	PEC02SAAN	Sullins Connector Solutions		
JP9			Header, 100 mil, 3 \times 1, tin, TH	Header, 3-pin, 100 mil, tin	PEC03SAAN	Sullins Connector Solutions		

Table 5. bq25600EVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
L2		1 μ H	Inductor, Wirewound, 1 μ H, 4 A, 0.041 Ω , SMD	4.06 x 4.06 mm	74437321010			
Q1	1	30 V	MOSFET, N-CH, 30 V, 22 A, DQK0006C (WSON-6)	DQK0006C	CSD17571Q2	Texas Instruments		None
R2, R16, R21, R27	0	0	Resistor, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED			
R3	1	1.00 k	Resistor, 1.00 k, 1%, 0.063 W, 0402	0402	CRCW04021K00FKED	Vishay-Dale		
R8	1	221	Resistor, 221, 1%, 0.063 W, 0402	0402	CRCW0402221RFKED	Vishay-Dale		
R9	1	2.80 k	Resistor, 2.80 k, 1%, 0.063 W, 0402	0402	CRCW04022K80FKED	Vishay-Dale		
R10, R11	2	10-k Ω	Trimmer, 10-k Ω , 0.25W, TH	4.5 x 8 x 6.7 mm	3266W-1-103LF	Bourns		
R12	1	158	Resistor, 158, 1%, 0.063 W, 0402	0402	CRCW0402158RFKED	Vishay-Dale		
R19, R20	0	200	Resistor, 200, 1%, 0.063 W, 0402	0402	CRCW0402200RFKED	Vishay-Dale		
R26	0	10	Resistor, 10, 5%, 0.063 W, 0402	0402	CRCW040210R0JNED	Vishay-Dale		
R29	0	10.0 k	Resistor, 10.0 k, 1%, 0.063 W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
SH-JP3, SH-JP5, SH-JP9, SH-JP11, SH-JP13, SH-JP14, SH-JP16	3	1 x 2	Fiducial mark. There is nothing to buy or mount.	Shunt	SNT-100-BK-G	Samtec	969102-0000-DA	3M
SW1, SW2, SW3, SW4	4		Compact probe tip circuit board test points, TH, 25 per ?	TH scope probe	131-5031-00	Tektronix		
TP12	0		Resistor, 10.0 k, 1%, 0.063 W, 0402	White miniature test point	5002	Keystone		

Table 6 lists the bq25600DEVM-771 BOM.

Table 6. bq25600DEVM-771 Bill of Materials

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
!PCB	1		Printed Circuit Board		PWR771	Any		
C1	1	1 μ F	Capacitor, ceramic, 1 μ F, 35 V, \pm 10%, X5R, 0603	0603	GMK107BJ105KA-T	Taiyo Yuden		
C3	1	10 μ F	Capacitor, ceramic, 10 μ F, 25 V, \pm 10%, X5R, 0805	0805	GRM21BR61E106KA73 L	Murata		
C6, C13	2	4.7 μ F	Capacitor, ceramic, 4.7 μ F, 16 V, \pm 10%, X5R, 0603	0603	GRM188R61C475KAAJ	Murata		
C7	1	0.047 μ F	Capacitor, ceramic, 0.047 μ F, 25 V, \pm 10%, X7R, 0402	0402	GRM155R71E473KA88 D	Murata		
C9, C10	2	10 μ F	Capacitor, ceramic, 10 μ F, 10 V, \pm 10%, X7R, 0805	0805	GRM21BR71A106KE51 L	Murata		
C15	1	1 μ F	Capacitor, ceramic, 1 μ F, 25 V, \pm 10%, X7R, 0805	0805	GRM219R71E105KA88 D	Murata		
C16	1	0.1 μ F	Capacitor, ceramic, 0.1 μ F, 25 V, \pm 10%, X7R, 0402	0402	GRM155R71E104KE14 D	Murata		
D4, D5	2	Green	LED, Green, SMD	1.6 x 0.8 x 0.8 mm	LTST-C190GKT	Lite-On		
H1, H2, H3, H4	4		Bumpon, Hemisphere, 0.44 x 0.20, Clear	Transparent Bumpon	SJ-5303 (CLEAR)	3M		
J1, J2, J4	3		Connector terminal block, 2 POS, 3.81 mm, TH	2-POS terminal block	1727010	Phoenix Contact		
J3	1		Connector, receptacle, Micro-USB Type B, R/A, bottom mount SMT	7.5 x 2.45 x 5 mm	0473460001	Molex		
J5	1		Terminal block receptacle, 3 x 1, 3.81 mm, R/A, TH	Terminal block, 3 POS	1727023	Phoenix Contact		
J6	1		Header (friction lock), 100 mil, 4x1, R/A, TH	4x1 R/A header	22-05-3041	Molex		
JP2, JP5, JP6, JP7, JP10, JP12, JP13, JP14	8		Header, 100 mil, 2x1, Tin, TH	Header, 2 pin, 100 mil, tin	PEC02SAAN	Sullins Connector Solutions		
JP4, JP8	2		Header, 100 mil, 3x1, Tin, TH	Header, 3 pin, 100 mil, tin	PEC03SAAN	Sullins Connector Solutions		
L1	1	1 μ H	Inductor, 1 μ H, 3.2 A, 0.028 Ω , SMD	2.5 x 2 mm	MPIM252010F1R0M-LF	Microgate		

Table 6. bq25600DEVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
LBL1	1		Thermal transfer printable labels, 0.650" W x 0.200" H – 10,000 per roll	PCB label 0.650" H x 0.200" W	THT-14-423-10	Brady		
R1	1	0.005	Resistor, 0.005, 1%, 0.25 W, AEC-Q200 Grade 1, 0603	603	ERJ3LWFR005V	Panasonic		
R4, R5, R6, R13, R24, R28, R29	7	10.0 k	Resistor, 10.0 k, 1%, 0.063 W, 0402	0402	CRCW040210K0FKED	Vishay-Dale		
R7, R17	2	2.21 k	Resistor, 2.21 k, 1%, 0.063 W, 0402	0402	CRCW04022K21FKED	Vishay-Dale		
R15	1	4.7 k	Resistor, 4.7 k, 5%, 0.063 W, 0402	0402	CRCW04024K70JNED	Vishay-Dale		
R22	1	5.23 k	Resistor, 5.23 k, 1%, 0.063 W, 0402	0402	CRCW04025K23FKED	Vishay-Dale		
R23	1	30.1 k	Resistor, 30.1 k, 1%, 0.063 W, 0402	0402	CRCW040230K1FKED	Vishay-Dale		
R25	1	0	Resistor, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
R30, R31, R32	3	0.01	Resistor, 0.01, 1%, 1 W, 2010	2010	WSL2010R0100FEA18	Vishay-Dale		
S1	0		Switch, normally open, 2.3-N force, 200-k operations, SMD	KSR	KSR221GLFS	C&K Components		
S2	1		Switch, SPST, 2 POS, 25 mA, 24 VDC, SMD	3.71x5.8mm	218-2LPST	CTS Electrocomponents		
SH-JP2, SH-JP4, SH-JP6, SH-JP7, SH-JP8, SH-JP10, SH-JP13, SH-JP14		1 x 2	Shunt, 100-mil, gold-plated, black	Shunt	SNT-100-BK-G	Samtec	969102-0000-DA	3M
TP1, TP2	2		Test point, miniature, red, TH	Red miniature test point	5000	Keystone		

Table 6. bq25600DEVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
TP3, TP4, TP6, TP7, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP21, TP24, TP25, TP26, TP27, TP28, TP29	18		Test point, miniature, white, TH	White miniature test point	5002	Keystone		
TP5, TP8	2		Test point, miniature, orange, TH	Orange miniature test point	5003	Keystone		
TP9	1		Test point, miniature, yellow, TH	Yellow miniature test point	5004	Keystone		
TP17, TP18, TP19, TP20, TP22, TP23	6		Test point, compact, SMT	Testpoint_Keystone_Compact	5016	Keystone		
U1	1		BQ25600DYFF, YFF0030ACAC (DSBGA-30)	YFF0030ACAC	BQ25600DYFFR	Texas Instruments	BQ25600DYFFT	Texas Instruments
C2, C5, C12	0	1000 pF	Capacitor, ceramic, 1000 pF, 25 V, ± 5%, C0G/NP0, 0402	0402	C1005C0G1E102J	TDK		
C4	0	10 µF	Capacitor, ceramic, 10 µF, 25 V, ± 10%, X7S, 0805	0805	GRM21BC71E106KE11L	Murata		
C8	0	110 pF	Capacitor, ceramic, 110 pF, 25 V, ± 5%, C0G/NP0, 0402	0402	GRM1555C1E111JA01D	Murata		
C11	0	0.1 µF	Capacitor, ceramic, 0.1 µF, 25 V, ± 20%, X7R, 0402	0402	C1005X7R1E104M050B	TDK		
C14, C20	0	4.7 µF	Capacitor, ceramic, 4.7 µF, 16 V, ± 10%, X5R, 0603	0603	GRM188R61C475KAAJ	Murata		
C17		10 µF	Capacitor, ceramic, 10 µF, 25 V, ± 10%, X5R, 0805	0805	GRM21BR61E106KA73L	MuRata		
C18		1 µF	Capacitor, ceramic, 1 µF, 35 V, ± 10%, X5R, 0603	0603	GMK107BJ105KA-T	Taiyo Yuden		
C19		10 µF	Capacitor, ceramic, 10 µF, 10 V, ± 10%, X7R, 0805	0805	GRM21BR71A106KE51L	MuRata		
D1		13 V	Diode, TVS, Uni, 13 V, W, SOD-123W	SOD-123W	PTVS13VS1UR,115	NXP Semiconductor		

Table 6. bq25600DEVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
D2, D7	1	40 V	Diode, Schottky, 40 V, 0.38 A, SOD-523	SOD-523	ZLLS350TA	Diodes Inc.		
D3, D6	0	20 V	Diode, Schottky, 20 V, 1 A, 152AD	152AD	NSR10F20NXT5G	ON Semiconductor		
FID1, FID2, FID3, FID4, FID5, FID6	0		Fiducial mark. There is nothing to buy or mount.	N/A	N/A	N/A		
J7	0		Header (shrouded), 100 mil, 5 × 2, high-temperature, gold, TH	5x2 Shrouded header	N2510-6002-RB	3M		
JP1, JP9	3		Header, 100 mil, 3 × 1, tin, TH	Header, 3 PIN, 100mil, Tin	PEC03SAAN	Sullins Connector Solutions		
JP3, JP11, JP15, JP16, JP17, JP18			Header, 100 mil, 2 × 1, tin, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins Connector Solutions		
L2		1 μ H	Inductor, Wirewound, 1 μ H, 4 A, 0.041 Ω , SMD	4.06x4.06mm	74437321010	Würth Elektronik		
Q1	1	30 V	MOSFET, N-CH, 30 V, 22 A, DQK0006C (WSON-6)	DQK0006C	CSD17571Q2	Texas Instruments		None
R2, R16, R21, R27	0	0	Resistor, 0, 5%, 0.063 W, 0402	0402	CRCW04020000Z0ED	Vishay-Dale		
R3	1	1.00 k	Resistor, 1.00 k, 1%, 0.063 W, 0402	0402	CRCW04021K00FKED	Vishay-Dale		
R8	1	221	Resistor, 221, 1%, 0.063 W, 0402	0402	CRCW0402221RFKED	Vishay-Dale		
R9	1	2.80 k	Resistor, 2.80 k, 1%, 0.063 W, 0402	0402	CRCW04022K80FKED	Vishay-Dale		
R10, R11	2	10-k Ω	Trimmer, 10-k Ω , 0.25W, TH	4.5x8x6.7mm	3266W-1-103LF	Bourns		
R12	1	158	Resistor, 158, 1%, 0.063 W, 0402	0402	CRCW0402158RFKED	Vishay-Dale		
R19, R20	0	200	Resistor, 200, 1%, 0.063 W, 0402	0402	CRCW0402158RFKED	Vishay-Dale		
R26	0	10	Resistor, 10, 5%, 0.063 W, 0402	0402	CRCW040210R0JNED	Vishay-Dale		
SH-JP1, SH-JP3, SH-JP5, SH-JP9, SH-JP11, SH-JP12, SH-JP15, SH-JP16	4	1 × 2	Shunt, 100-mil, Gold-plated, black	Shunt	SNT-100-BK-G	Samtec	969102-0000-DA	3M

Table 6. bq25600DEVM-771 Bill of Materials (continued)

Designator	QTY	Value	Description	Package Reference	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
SW1, SW2, SW3, SW4	4		Compact probe tip circuit board test points, TH, 25 per	TH Scope Probe	131-5031-00	Tektronix		
TP12	0		Test point, miniature, white, TH	White Miniature Test point	5002	Keystone		

STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
 - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductor products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
 - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
 - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
 - 3.1 *United States*
 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

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3.4 *European Union*

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

6. *Disclaimers:*
- 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
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7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.
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- 8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS , REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.
- 8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, , EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.
9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.
10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

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